STRIVE
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Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2025-04-03
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
Antonella Lanzafame
Date: 2025.04.03
15:01:57 CEST

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VIPER114BLSTR	SSW4*MY4NAA5	A	Z9LA	2025-04-03
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	81	mg	Each	ECOPACK® 3
Identity	**Authority**			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape	
DSO	4.85x3.9	10	gull wing	
Comment				
Comment	W4 SSOP 10L 3.9 BODY 1 PITCH			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false

Exemption Id.	**Description**

QueryList : California Prop65 list, dated 3rd January 2025			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	**amount in product (mg)**	**Application**	**ppm in product**
Nickel	0.020	alloy	247
Lead	0.002	solder	25

QueryList :Customer	**Response**
QUERY	**Response**

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				**Response**
QUERY				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	**Cadmium (Cd)**	**Mercury (Hg)**	**Hexavalent Chromium (Cr VI)**	**PBB & PBDE**
O	O	O	O	O

QueryList : REACH-21st January 2025				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
,			,	

QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Gold, Tin, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**SSW4*MY4NAA5**		80.9998		6000001.0	999996.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Dies	M-011 Other inorganic materials	3.449	mg	supplier	die	Silicon(Si)	7440-21-3		3.321	mg	962888	41000
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.044	mg	12757	543
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.001	mg	290	12
				supplier	metallisation	Copper(Cu)	7440-50-8		0.001	mg	290	12
				supplier	metallisation	Gold(Au)	7440-57-5		0.005	mg	1450	62
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.020	mg	5799	247
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	290	12
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	290	12
				supplier	metallisation	Vanadium(V)	7440-62-2		0.001	mg	290	12
				supplier	Passivation	Silicon nitride(S	12033-89-5		0.012	mg	3479	148
				supplier	passivation	Silicon oxide	7631-86-9		0.034	mg	9858	420
				supplier	polymer coating	polyimide	proprietary		0.008	mg	2320	99
Leadframe	M-004 Copper and its alloys	30.300	mg	supplier	alloy	Copper(Cu)	7440-50-8		28.268	mg	932937	348988
				supplier	alloy	Iron(Fe)	7439-89-6		0.758	mg	25017	9358
				supplier	alloy	Phosphorus(P)	7723-14-0		0.030	mg	990	370
				supplier	alloy	Zinc(Zn)	7440-66-6		0.030	mg	990	370
				SVHC	alloy	Lead(Pb)	7439-92-1		0.002	mg	66	25
				supplier	alloy	Silver (Ag)	7440-22-4		1.212	mg	40000	14963
Die attach	M-011 Other inorganic materials	0.520	mg	supplier	glue	Silver(Ag)	7440-22-4		0.423	mg	813462	5222
				supplier	glue	Acrylate resins	7534-94-3		0.062	mg	119231	765
				supplier	glue	Heterocyclic or	3006-93-7		0.016	mg	30769	198
				supplier	glue	Fluoroaliphatic	1017237-78-3		0.003	mg	5769	37
				supplier	glue	Treated silica	proprietary		0.016	mg	30769	198
Bonding wires	M-004 Copper and its alloys	0.700	mg	supplier	wire	Cu	7440-50-8		0.679	mg	970000	8383
	0			supplier	wire	Pd	7440-05-3		0.021	mg	30000	259
Encapsulation	M-011 Other inorganic materials	44.031	mg	supplier	mold compound	Epoxy Resin 1	29690-82-2		0.246	mg	5587	3037
				supplier	mold compound	Epoxy Resin 2	proprietary		0.246	mg	5587	3037
				supplier	mold compound	Epoxy Resin 3	proprietary		0.246	mg	5587	3037
				supplier	mold compound	Phenol Resin	25068-38-6		0.902	mg	20486	11136
				supplier	mold compound	Carbon black	1333-86-4		0.041	mg	931	506
				supplier	mold compound	Amorphous sili	60676-86-0		41.366	mg	939474	510691
				supplier	mold compound	Crystal silica	14808-60-7		0.984	mg	22348	12148
Connections coating	Solder	2.000	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		2.000	mg	1000000	24689